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(12) **United States Design Patent**
Higashibata

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(54) **SEMICONDUCTOR MODULE**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

(21) Appl. No.: **29/238,804**

(22) Filed: **Sep. 22, 2005**

(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
257/177, 197, 666, 684, 686, 689, 775; 361/820
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a semiconductor module showing our new design;

FIG. 2 is a rear view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

FIG. 5 is a left side view thereof; and,

FIG. 6 is a right side view thereof.

The broken lines shown in the drawings are for illustrative purposes only and form no part of the claimed design.

1 Claim, 2 Drawing Sheets

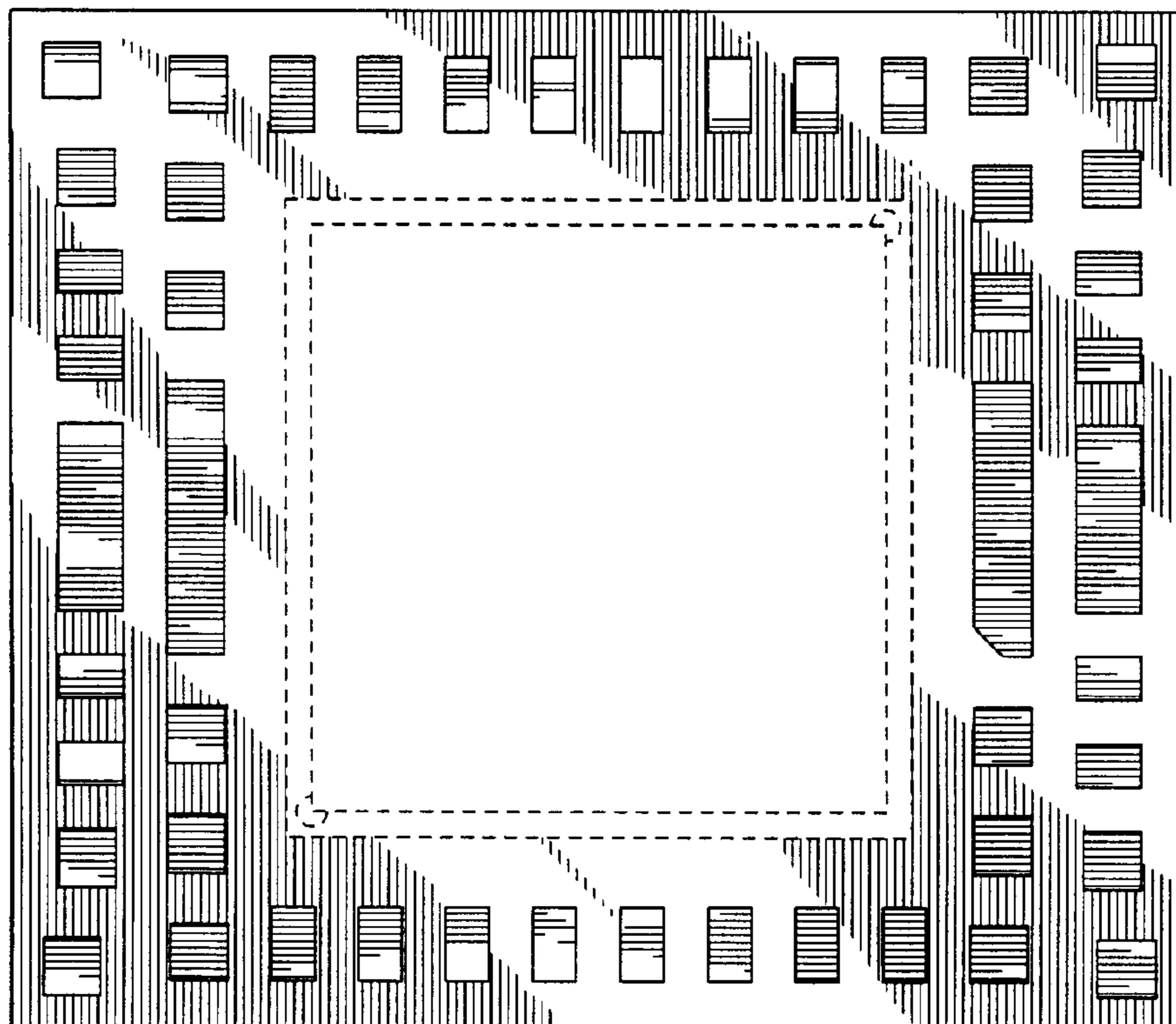


FIG.1

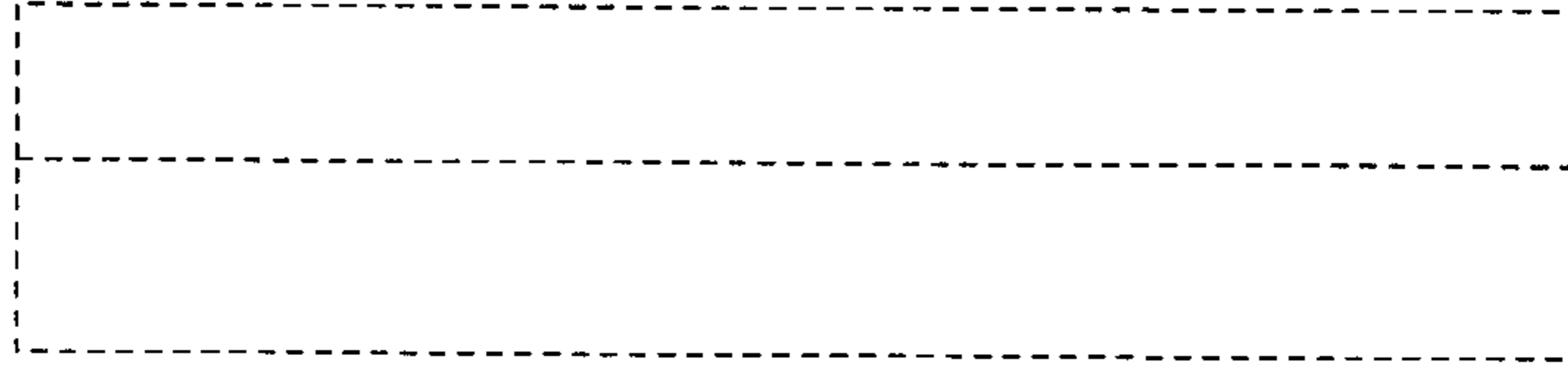


FIG.2

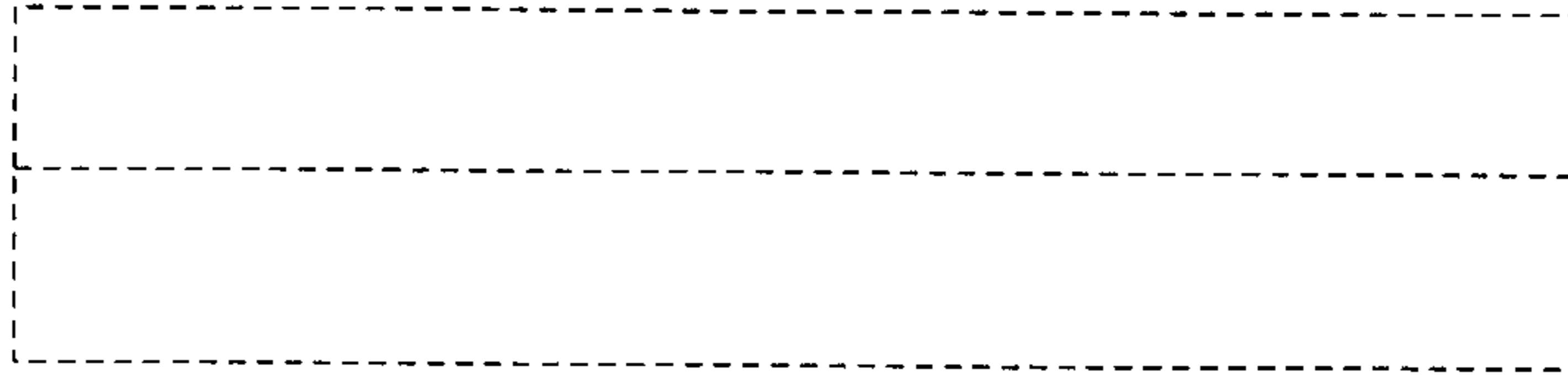


FIG.3

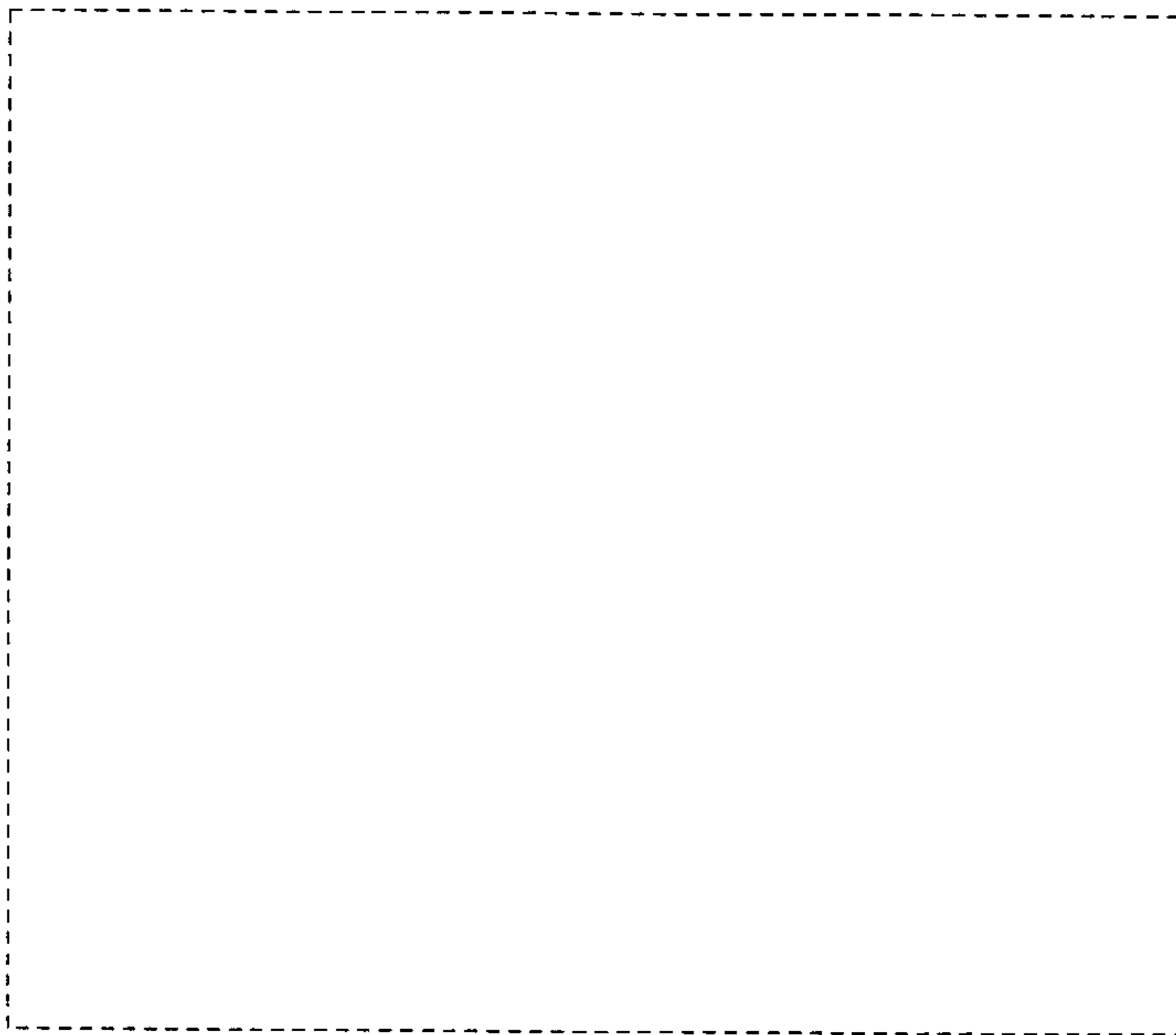


FIG.4

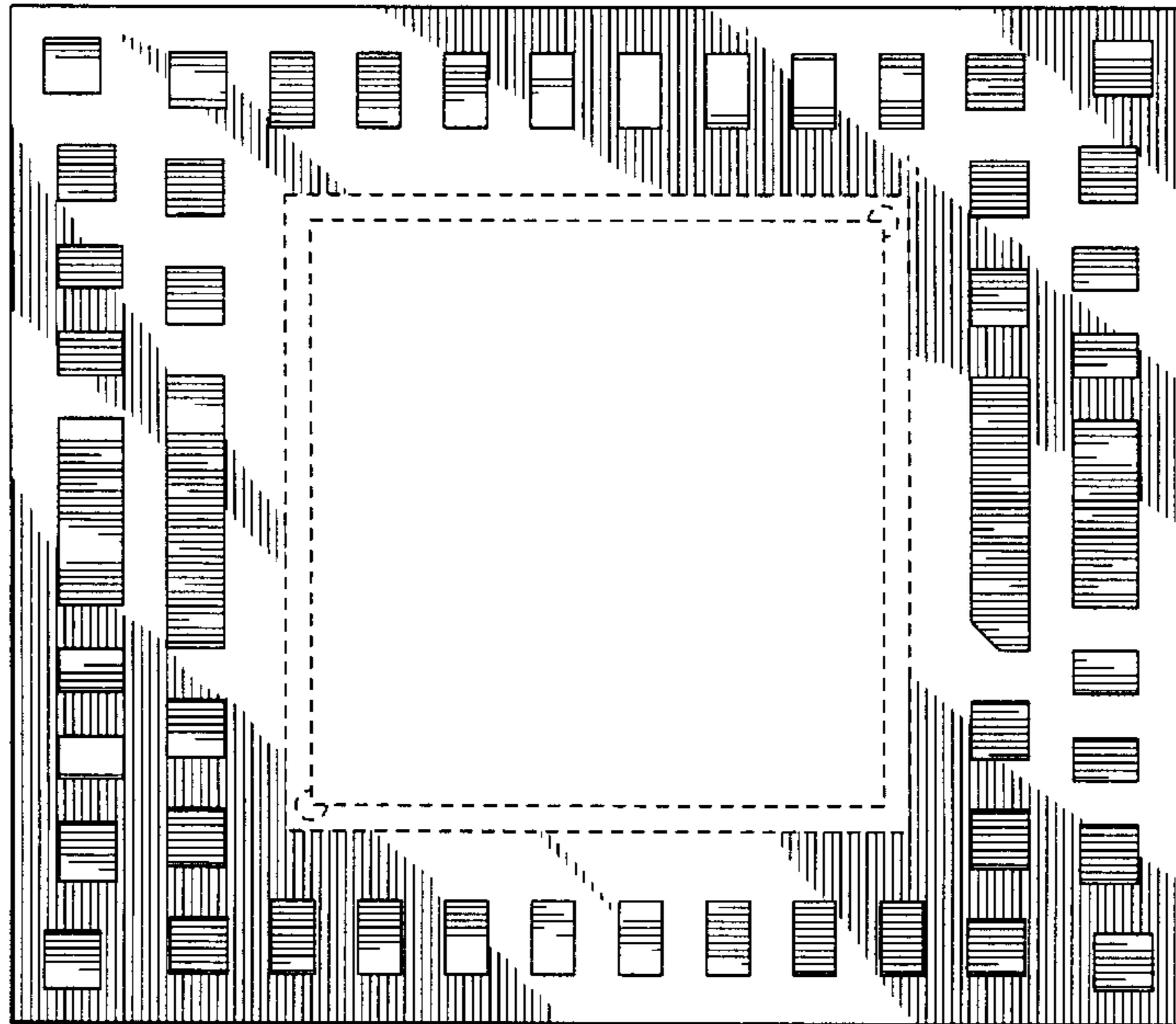


FIG.5

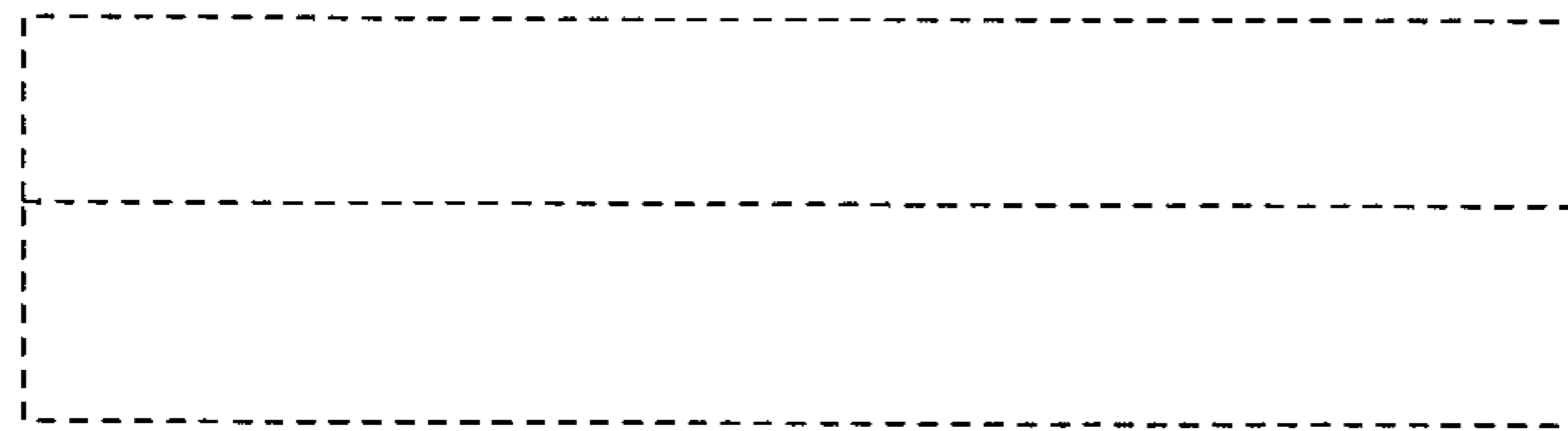


FIG.6

